

To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HD74HC05

Hex Inverters (with Open Drain Outputs)

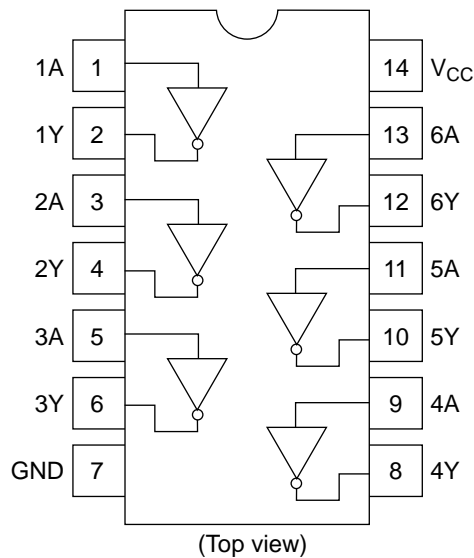
RENESAS

ADE-205-407 (Z)
1st. Edition
Sep. 2000

Features

- High Speed Operation: $t_{pd} = 8 \text{ ns typ}$ ($C_L = 50 \text{ pF}$)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2 \text{ to } 6 \text{ V}$
- Low Input Current: $1 \mu\text{A max}$
- Low Quiescent Supply Current: $I_{CC}(\text{static}) = 1 \mu\text{A max}$ ($T_a = 25^\circ\text{C}$)

Pin Arrangement



DC Characteristics

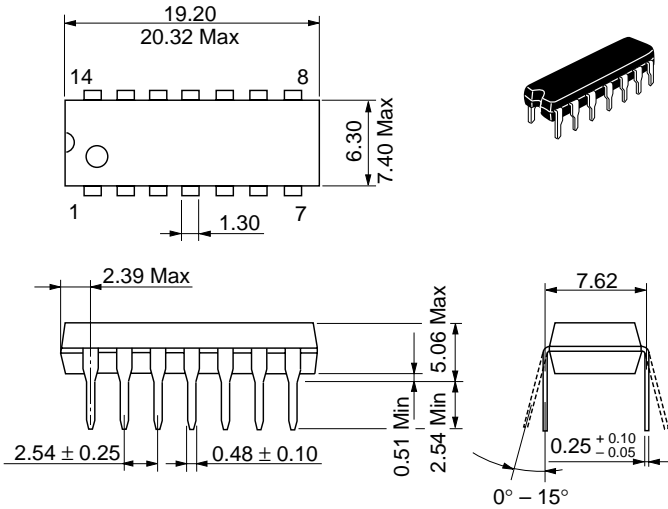
| Item | Symbol | V _{CC} (V) | Ta = 25°C | | | Ta = -40 to +85°C | | Unit | Test Conditions |
|--------------------------|----------------------|---------------------|-----------------|-----|------|-------------------|------|--------------------------|---|
| | | | Min | Typ | Max | Min | Max | | |
| Input voltage | V _{IH} | 2.0 | 1.5 | — | — | 1.5 | — | V | |
| | | 4.5 | 3.15 | — | — | 3.15 | — | | |
| | | 6.0 | 4.1 | — | — | 4.2 | — | | |
| | V _{IL} | 2.0 | — | — | 0.5 | — | 0.5 | V | |
| | | 4.5 | — | — | 1.35 | — | 1.35 | | |
| | | 6.0 | — | — | 1.8 | — | 1.8 | | |
| Off-state output current | I _O (off) | 6.0 | — | — | ±0.5 | — | ±5.0 | μA | V _{in} = V _{IH} or V _{IL} V _{out} = V _{CC} or GND |
| Output voltage | V _{OL} | 2.0 | — | 0.0 | 0.1 | — | 0.1 | V | V _{in} = V _{IH} or V _{IL} I _{OL} = 20 μA |
| | | 4.5 | — | 0.0 | 0.1 | — | 0.1 | | |
| | | 6.0 | — | 0.0 | 0.1 | — | 0.1 | | |
| | | 4.5 | — | — | 0.26 | — | 0.33 | I _{OL} = 4 mA | |
| | | 6.0 | — | — | 0.26 | — | 0.33 | I _{OL} = 5.2 mA | |
| | | Input current | I _{in} | 6.0 | — | — | ±0.1 | — | |
| Quiescent supply current | I _{CC} | 6.0 | — | — | 1.0 | — | 10 | μA | V _{in} = V _{CC} or GND, I _{out} = 0 μA |

AC Characteristics (C_L = 50 pF, Input t_r = t_f = 6 ns)

| Item | Symbol | V _{CC} (V) | Ta = 25°C | | | Ta = -40 to +85°C | | Unit | Test Conditions |
|------------------------|------------------|---------------------|-----------|-----|-----|-------------------|-----|------|-----------------|
| | | | Min | Typ | Max | Min | Max | | |
| Propagation delay time | t _{LZ} | 2.0 | — | — | 90 | — | 115 | ns | |
| | | 4.5 | — | 10 | 18 | — | 23 | | |
| | | 6.0 | — | — | 15 | — | 20 | | |
| | t _{ZL} | 2.0 | — | — | 90 | — | 115 | ns | |
| | | 4.5 | — | 6 | 18 | — | 23 | | |
| | | 6.0 | — | — | 15 | — | 20 | | |
| Output fall time | t _{THL} | 2.0 | — | — | 75 | — | 95 | ns | |
| | | 4.5 | — | 5 | 15 | — | 19 | | |
| | | 6.0 | — | — | 13 | — | 16 | | |
| Input capacitance | C _{in} | — | — | 5 | 10 | — | 10 | pF | |

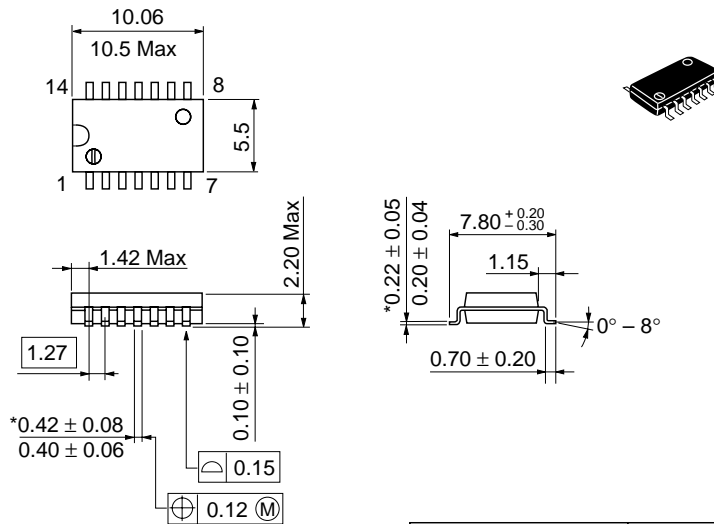
Package Dimensions

Unit: mm



| | |
|------------------------|----------|
| Hitachi Code | DP-14 |
| JEDEC | Conforms |
| EIAJ | Conforms |
| Mass (reference value) | 0.97 g |

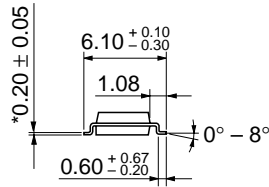
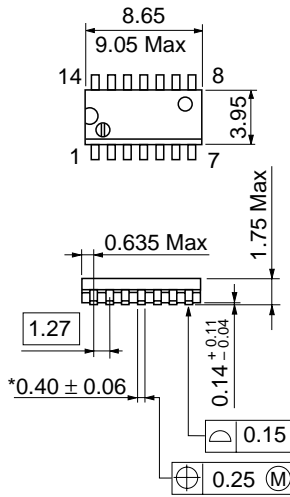
Unit: mm



*Dimension including the plating thickness
Base material dimension

| | |
|------------------------|----------|
| Hitachi Code | FP-14DA |
| JEDEC | — |
| EIAJ | Conforms |
| Mass (reference value) | 0.23 g |

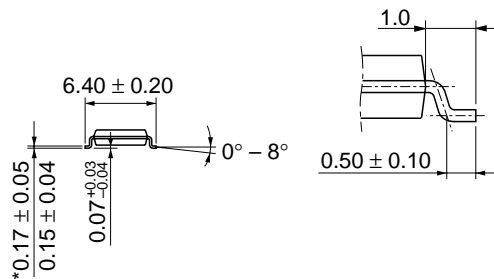
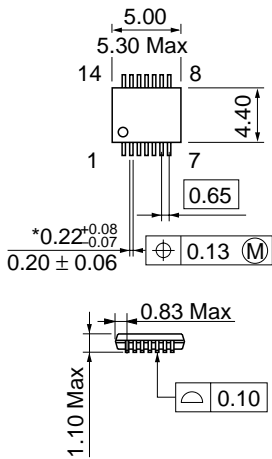
Unit: mm



*Pd plating

| | |
|------------------------|----------|
| Hitachi Code | FP-14DN |
| JEDEC | Conforms |
| EIAJ | Conforms |
| Mass (reference value) | 0.13 g |

Unit: mm



*Dimension including the plating thickness
Base material dimension

| | |
|------------------------|---------|
| Hitachi Code | TTP-14D |
| JEDEC | — |
| EIAJ | — |
| Mass (reference value) | 0.05 g |

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